

Title (en)

PROCESS FOR THE PREPARATION OF AN ADDITIVE FOR AN ACID BATH FOR THE ELECTRODEPOSITION OF COPPER AND USE THEREOF

Publication

**EP 0071512 B1 19850605 (FR)**

Application

**EP 82401328 A 19820716**

Priority

FR 8114394 A 19810724

Abstract (en)

[origin: US4430173A] Additive composition for an acid copper electroplating bath, which bath being well adapted for the copper plating of printed circuits, is comprised of (1) the sodium salt of omega -sulfo-n-propyl N,N-diethyldithiocarbamate, (2) polyethylene glycol having an average molecular weight ranging from about 6,000 to 20,000, (3) crystal violet, and (4) sulfuric acid.

IPC 1-7

**C25D 3/38**

IPC 8 full level

**H05K 3/18** (2006.01); **C25D 3/38** (2006.01); **C25D 7/00** (2006.01)

CPC (source: EP US)

**C25D 3/38** (2013.01 - EP US)

Cited by

DE4032864A1; CN110284163A; DE4126502C1; US5433840A; DE19758121A1; DE19758121C2; DE10337669A1; DE10337669B4

Designated contracting state (EPC)

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**EP 0071512 A1 19830209; EP 0071512 B1 19850605**; AT E13697 T1 19850615; DE 3264038 D1 19850711; FR 2510145 A1 19830128; FR 2510145 B1 19860207; HK 96586 A 19861219; IE 53352 B1 19881026; IE 821754 L 19830124; JP S5827992 A 19830218; JP S6155599 B2 19861128; SG 64086 G 19870918; US 4430173 A 19840207

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**EP 82401328 A 19820716**; AT 82401328 T 19820716; DE 3264038 T 19820716; FR 8114394 A 19810724; HK 96586 A 19861211; IE 175482 A 19820722; JP 12684882 A 19820722; SG 64086 A 19860724; US 39880582 A 19820716